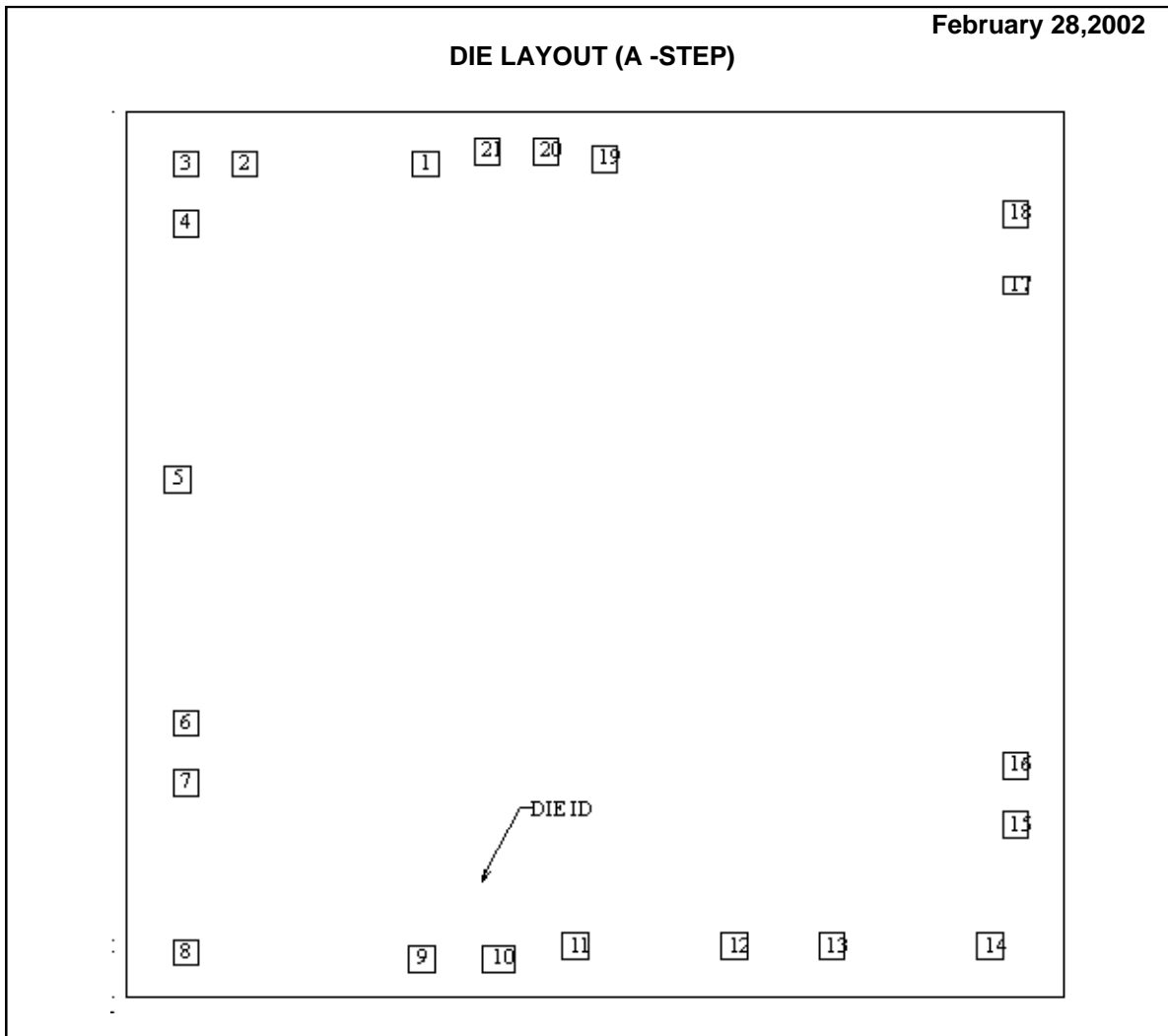


**ADC0804 MDC MWC  
8-BIT  $\mu$ P COMPATIBLE A/D CONVERTERS**



**DIE/WAFER CHARACTERISTICS**

Fabrication Attributes		General Die Information	
Physical Die Identification	ADC08A	Bond Pad Opening Size (min)	89 $\mu$ m x 57 $\mu$ m
Die Step	A	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	100mm	Back Side Metal	Unground
Die Size (Drawn)	3226 $\mu$ m x 3048 $\mu$ m 127mils x 120mils	Back Side Connection	Floating
Thickness	406 $\mu$ m Nominal		
Min Pitch	203 $\mu$ m Nominal		

**Special Assembly Requirements:**

**Note: Actual die size is rounded to the nearest micron.**

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Die Bond Pad Coordinate Locations (A -Step)						
(Referenced to die center, coordinates in $\mu$ m) NC = No Connection						
SIGNAL NAME	PAD# NUMBER	X/Y COORDINATES		PAD SIZE		
		X	Y	X	Y	
/CS	1	-584	1341	89	x	89
/RD	2	-1207	1341	89	x	89
/WR	3	-1410	1341	89	x	89
Clk in	4	-1410	1138	89	x	89
/INTR	5	-1440	254	89	x	89
Vin+	6	-1410	-584	89	x	89
Vin-	7	-1410	-787	89	x	89
A GND	8	-1410	-1373	89	x	86
Vref/2	9	-597	-1397	89	x	89
D GND	10	-333	-1397	114	x	89
DB7(MSB)	11	-69	-1352	89	x	91
DB6	12	478	-1352	89	x	91
DB5	13	815	-1352	89	x	91
DB4	14	1361	-1352	89	x	91
DB3	15	1448	-934	89	x	89
DB2	16	1448	-731	89	x	89
DB1	17	1448	924	89	x	57
DB0(LSB)	18	1448	1169	89	x	89
Clk R	19	33	1359	89	x	89
Vcc (or Vref)	20	-170	1385	89	x	89
Vcc (or Vref)	21	-373	1385	89	x	89

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